

MSTCONN

东莞市钜明科技有限公司
DONG GUAN JU MING TECHNOLOGY CO.,LTD

承 认 书

品 名: SD CARD CONNECTOR PUSH TYPE
料 号: SD01/02-AP1**-**
日 期: 2006/12/09

客户:

采购部	工程部	批准

钜明:

工程部	销售部	批准
曾广明 12/09`06		

东莞市钜明科技有限公司

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PRODUCT SPECIFICATION

品 名 (Title): SD CARD CONNECTOR PUSH TYPE料号 (Part Number): SD01/02-AP1**-**文件编号 (Spec. No.): SP-TH01版本 (Revision): A

修 订 记 录

版本 Rev.	ECN 编号 ECN Number	修 订 内 容	修订日期 Issue Date
A		新制定	2006/10/6

核准 (Approved By)	审核 (Checked By)	制订 (Originator)
曾广明 10/08`06	曾广明 10/08`06	纪芳

SD CONNECTOR PUSH-PUSH TYPE

1. SCOPE

This specification covers performance, tests and quality requirements for SD CONNECTOR PUSH TYPE.

2. APPLICABLE DOCUMENT

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

1.1 Commercial Standards And Specification

IEC 512 Electromechanical components for electronic equipment; basic testing procedures and measuring methods

EIA 364 Test methods for electrical connectors

UL-STD-94 Tests for flammability of plastic materials for parts in devices and appliances

3. REQUIREMENTS

3.1 DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing

3.2 MATERIALS

A. Housing: LCP, UL94V-0, Color; black

B. Contact: Phosphor Bronze

Finish: (a) Contact Area: Au plated over Nickel

(b) Solder Tail: tin/Lead plated over Nickel or Unload plated over Nickel

(c) Under plated: Nickel plated overall

C. Cover: Stainless steel

Finish: (a) Solder tail: Au plated over Nickel

(b) Under plated: Nickel plated overall

3.3 RATINGS

A. Current Rating 0.5A

B. Voltage Rating : 5V

C. Operating temperature : -2.5°C to 90°C

Storage temperature : -40°C to 90°C

Humidity : 95% max. non condensing

3.4 TEST CONDITION

The product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1.

3.5 TEST REQUIREMENTS AND PROCEDURES SUMMARY

TEST DESCRIPTION	REQUIREMENT	PROCEDURED
Examination of product	Meets requirements of product drawing and proconn specification	Visual inspection No physical damage
ELECTRICAL		
Contact Resistance	100mΩ Max. Write protect contact 150mΩ Max. Card detect contact 150mΩ Max.	IEC 512part2, test 2a, except 100mA maximum test current and 20V maximum open circuit voltage
Insulation Resistance	1000MΩ Min, initial 100MΩ Min, final	500VDC IEC 512 part2, test3a, method C
Dielectric Withstanding Voltage Resistance	No creeping discharge or flashes occur. Current Leak 1mA Max.	500V AC 1 minute, Test between adjacent contact of unmated samples ESA-364-20
MECHANICAL		
Total pulling and Insertion force	Total Pulling Force: 2N Min Total Insertion Force: 40N Max.	IEC 512part7, at a rate of 25mm/minute
Vibration and High Frequency	No physical damage	IEC 512 part4, test6c. Mechanical frequency range is 10~2000Hz, acceleration is 2G
Shock	No physical damage	IEC 512 part4, test6c. Acceleration is 5G
Contact Force	2N~20N	IEC 512 Part8
Connector Intensity	No. physical damage	Applied Force 10N to main body of connector at no card for Up/Down Forward/Backward
Wrestling (Flapping) Strength	No. physical damage	Applied Force 10N to SD card for UP/Down/Right/Left directions (the card shall be inserted 15mm into the connector the head of the card)
Durability Cycling	No physical damage	Operation Cycles: 10000 cycles (push-in push-out) time mate and unmated connectors for 500 cycles per hour EIA364-09

ENVIRONMENTAL		
Humidity	Contact resistance;100m Ω Max. initial;20M Ω change after test. Insulation resistance;Initial.1000M Ω .after test 100MΩ	Temperature;40°C+/-2°C Flumidity;90~95%(RH) Period: 96 hours. MIL-STD-202F, method 103B, Test condition; B
Salt Spray	No harmful corrosion	Temperature;35°C+/-2°C Concentration:5% Period:48 hours. MIL-STD-203F, method 101D.
Thermal Shock	No physical damage	MIL-STD-202F ,METHOD 107G, Test condition A:-55 to+85°C ,5 cycles.
Moisture Resistance	No physical damage	MIL-STD-202, Method106, test condition B, subject mated connectors to 10 cycles Between-10 °C and 65 °C at 80 ~ 98% relative Humidity.
High Temperature Resistance	No physical damage	MIL-STD-2025, Method108, subject mated connectors to 85°C for 250 hours.
PHYSICAL		
Solder ability	The test area shall be covered more than95% of immersed area with flash solder.	Solder temperature:230°C+/-5°C Unload plated solder temperature;245 °C +/-3 °C period:5+/-0.5sec; MIL-STD-202F ,method 208
Resistance to Reflow Soldering Heat	NO physical abnormalities such as Crack and deformation of housing, shall be present after the test.	Pre-Heat 150~200°C:60 sec maximum. Heat 265°C+/-5 °C 5sec (270°Cmaximum),2 cycles. Method 210 Condition: k

Figure 1

3.6 PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

Test or Examination	Test Group									
	A	B	C	D	E	F	G	H	I	J
Examination of product	1, 9	1, 8	1, 5	1, 7	1, 6	1, 5	1, 9	1, 9	1, 9	1, 9
Contact Resistance	2, 6	2, 7	2, 4	2, 5	2	2, 4	2, 6	2, 6	2, 6	2, 6
Insulation Resistance	3, 7			3, 6			3, 7	3, 7	3, 7	3, 7
DWV	4, 8						4, 8	4, 8	4, 8	4, 8
Total pulling and Insertion Force		3, 6								
Vibration and High Frequency			3							
Shock				4						
Contact Force					3					
Connector Intensity		4								
Wrestling Strength					4					
Durability Cycling		5								
Humidity	5									
Salt Spray						3				
Solder ability					5					
Thermal Shock							3			
Moisture Resistance								5		
High Temperature Resistance									5	
Resistance to Reflow Soldering Heat										5

NOTE:

(a) Numbers indicate sequence in which tests are performed.

TEST REPORT

品名(Title): SD CARD CONNECTOR PUSH TYPE

料号(Part Number): SD01/02-AP1**-**

文件编号(Spec. No.): SP-TH01

版本(Revision): A

修 订 记 录

版本 Rev.	ECN 编号 ECN Number	修 订 内 容	修订日期 Issue Date
A		新制定	2006/10/6

核准(Approved By)	审核(Checked By)	制订(Originator)
曾广明 10/08`06	曾广明 10/08`06	纪芳

SD CONNECTOR PUSH TYPE

1. INTRODUCTION

1.1 Purpose

Testing was performed on the PROCONN SD CONNECTOR PUSH TYPE to determine its conformance to the requirements of PROCONN Project Specification.

1.2 Scope

This report covers the electrical, mechanical, and environmental performance of SD CONNECTOR PUSH TYPE manufactured by the PROCONN.

1.3 Conclusion

SD CONNECTOR PUSH TYPE meets the electrical, mechanical, and environmental performance requirements of PROCONN Product Specification

1.4 Product Description

The PROCONN SD CONNECTOR PUSH TYPE applied at primed circuit board (PCB). The contacts are made from copper alloy with gold plating on the contact interface and tin-lead plating or Unload plated on the solder tail, all over Nickel plating. The housing material is LCP insulating polymer, UL94V-0.

1.5 Test Samples

The test samples were randomly selected from normal current production lots, and the following part numbers were used for test.

Test Group	Quantity	Part Number	Description
A, B, C, D, E, F, G, H, I, J,	6ea.	SDC009 PUSH TYPE SERIES	SD CONNECTOR PUSH TYPE

1.6. Qualification Test Sequence

Test or Examination	Test Group									
	A	B	C	D	E	F	G	H	I	J
Examination of product	1, 9	1, 8	1, 5	1, 7	1, 6	1, 5	1, 9	1, 9	1, 9	1, 9
Contact Resistance	2, 6	2, 7	2, 4	2, 5	2	2, 4	2, 6	2, 6	2, 6	2, 6
Insulation Resistance	3, 7			3, 6			3, 7	3, 7	3, 7	3, 7
DWV	4, 8						4, 8	4, 8	4, 8	4, 8
Total pulling and Insertion Force		3, 6								
Vibration and High Frequency			3							
Shock				4						
Contact Force					3					
Connector Intensity		4								
Wrestling Strength					4					
Durability Cycling		5								
Humidity	5									
Salt Spray						3				
Solder ability					5					
Thermal Shock							3			
Moisture Resistance								5		
High Temperature Resistance									5	
Resistance to Reflow Soldering Heat										5

NOTE: (a) The numbers indicate sequence in which tests were performed.
Figure

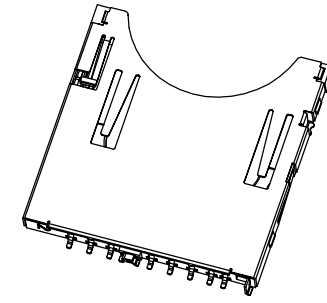
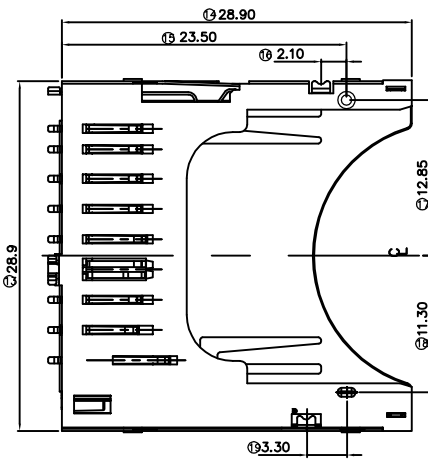
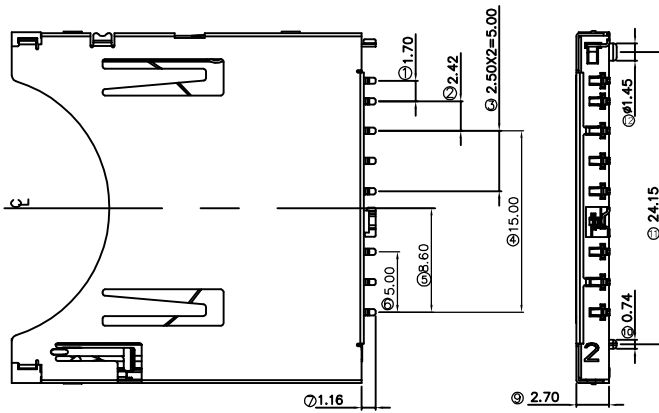
2. TEST RESULT

GP	TEST	SPEC.	DATA		
			Mean	Max.	Min.
A	Contact Resistance	100mΩ Max.	29.12 mΩ	32.85 mΩ	25.77 mΩ
	Insulation Resistance	1000MΩ Min.	ok	ok	ok
	DWV	500V AC ms	ok	ok	ok
	Humidity	40°C, 96hrs	ok	ok	ok
	Contact Resistance	100 mΩ Max.	32.15 mΩ	34.97 mΩ	28.45 mΩ
	Insulation Resistance	100 MΩ Min.	ok	ok	ok
	DWV	500V AC ms	ok	ok	ok
	Appearance	No Damage	ok	ok	ok
B	Contact Resistance	100 mΩ Max.	29.06 mΩ	32.97 mΩ	25.75 mΩ
	Total Pulling and Insertion Force	2N~40N	9.27N	9.38N	8.07N
	Connector Intensity	No Damage(10N)	ok	ok	ok
	Durability Cycling	5000 cycles	ok	ok	ok
	Total Pulling and Insertion Force	2N~40N	10.57N	12.83N	10.56N
	Contact Resistance	100 mΩ Max.	34.15 mΩ	37.84 mΩ	26.98 mΩ
	Appearance	No Damage	OK	OK	OK
C	Contact Resistance	100 mΩ Max.	28.87 mΩ	32.99 mΩ	29.74 mΩ
	Vibration and High Frequency	10~2000Hz, 2G	OK	OK	OK
	Contact Resistance	100 mΩ Max.	45.88 mΩ	46.82 mΩ	39.78 mΩ
	Appearance	No Damage	OK	OK	OK
D	Contact Resistance	100 mΩ Max.	29.78 mΩ	32.75 mΩ	26.53 mΩ
	Insulation Resistance	1000MΩ Min.	OK	OK	OK
	Shock	No Damage	OK	OK	OK
	Insulation Resistance	100 mΩ Min.	OK	OK	OK
	Contact Resistance	100 mΩ Max.	32.89 mΩ	34.86 mΩ	26.55 mΩ
	Appearance	No Damage	OK	OK	OK
E	Contact Resistance	100 mΩ Max.	27.88 mΩ	32.02 mΩ	26.18 mΩ
	Contact Force	0.2~0.4N	0.28N	0.37N	0.25N
	Wrestling Strength	No Damage(10N)	OK	OK	OK
	Solder ability	Covered more than95%	OK	OK	OK
	Appearance	No Damage	OK	OK	OK
F	Contact Resistance	100 mΩ Max.	32.11 mΩ	35.20 mΩ	29.32 mΩ
	Salt Spray	35°C, 48hrs	OK	OK	OK
	Contact Resistance	100 mΩ Max.	34.23 mΩ	37.96 mΩ	32.44 mΩ
	Appearance	No Damage	OK	OK	OK

Figure 2(Cont)

GP	TEST	SPEC.	DATA		
			Mean	Max.	Min
G	Contact Resistance	100mΩ Max.	30.11 mΩ	34.45 mΩ	29.17 mΩ
	Insulation Resistance	1000MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
	Thermal Shock	-55°C to ÷ 85°C, 5Cycles	0k	0k	0k
	Contact Resistance	100mΩ Max.	35.25 mΩ	39.97 mΩ	29.55 mΩ
	Insulation Resistance	100 MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
H	Contact Resistance	100mΩ Max.	26.12 mΩ	31.86 mΩ	22.33 mΩ
	Insulation Resistance	1000MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
	Moisture Resistance	-10°C and 65°C, 10Cycles	0k	0k	0k
	Contact Resistance	100mΩ Max.	32.41 mΩ	33.97 mΩ	26.21 mΩ
	Insulation Resistance	100 MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
I	Contact Resistance	100mΩ Max.	30.87 mΩ	31.48 mΩ	26.57 mΩ
	Insulation Resistance	1000mΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
	High Temperature Resistance	85°C, 250hr	0k	0k	0k
	Contact Resistance	100mΩ Max.	37.15 mΩ	39.87 mΩ	30.45 mΩ
	Insulation Resistance	100 MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
J	Contact Resistance	100mΩ Max.	30.11 mΩ	36.11 mΩ	30.28 mΩ
	Insulation Resistance	1000MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k
	Resistance to Reflow Soldering Heat	No Damage	0k	0k	0k
	Contact Resistance	100mΩ Max.	31.15 mΩ	33.97 mΩ	29.35 mΩ
	Insulation Resistance	100 MΩ Min.	0k	0k	0k
	DWV	500VAC rms.	0k	0k	0k

Figure2 (End)

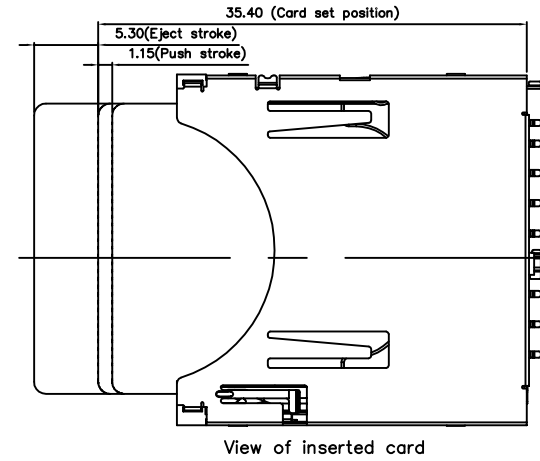
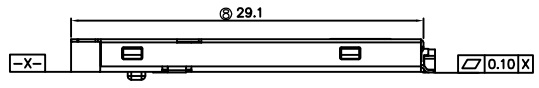


SPECIFICATION

1.Material:
 Insulator: LCP, rated UL94V-0,color:black.
 Contacts: Phosphor Bronze,
 Tin 160u" at Solder Tail,
 Selected Gold on Contact Area Plating.
 Ground:Phosphor Bronze,Tin 160u".
 Shell: Stainless.

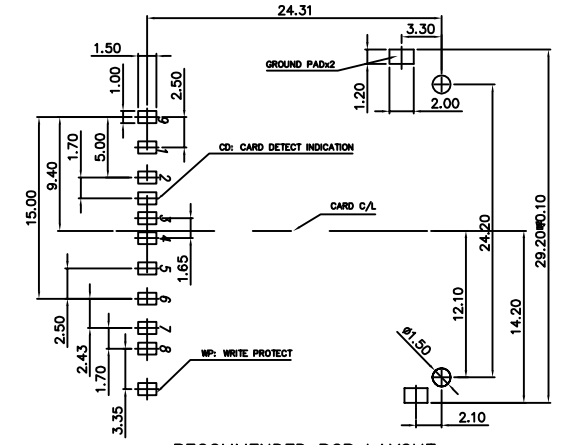
2.Electrical Characteristics:
 Operating voltage : 250V(AC/DC).
 Current rating : 0.5 A.
 Operating Temperature: -20°C~+65°C.
 Insulation resistance: 1000M ohms min. at 250VDC
 Dielectric withstanding voltage:500 VAC/1minute.
 Contact resistance: 100m ohms max.
 Mating cycle: 10000 cycles, spring is not breaking.

Pin No.	SD	MMC
P1	MMC-DAT3 SD-CD/DAT3	1P
P2	MMC-CMD SD-CMD	2P
P3	MMC-VSS1 SD-VSS1	3P
P4	MMC-VDD SD-VDD	4P
P5	MMC-CLK SD-CLK	5P
P6	MMC-VSS2 SD-VSS2	6P
P7	MMC-DAT0 SD-DAT0	7P
P8	SD-DAT1	8P
P9	SD-DAT2	9P

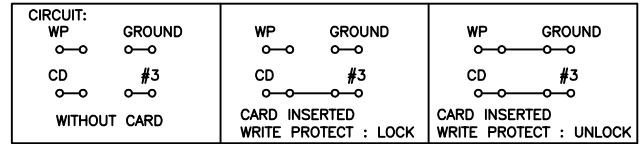


PART. NO. :
SD01-AP1**-**

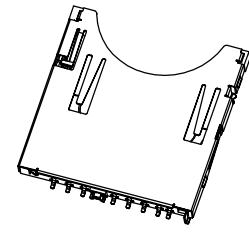
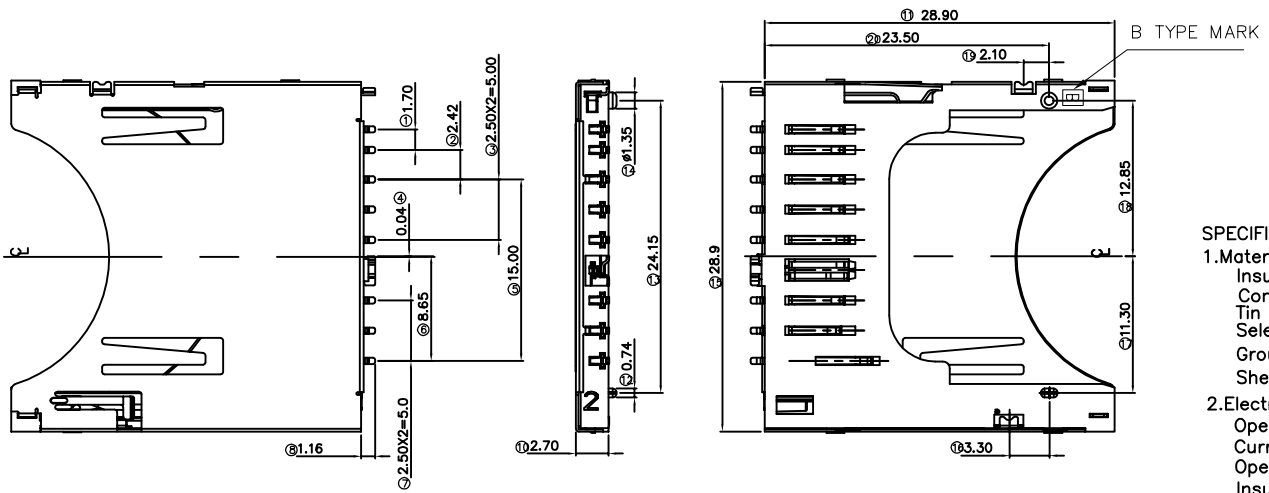
- 44: 功能区镀金5U", 锡脚镀亮纯锡至少160U"
- 45: 功能区镀金10U", 锡脚镀亮纯锡至少160U"
- 01: 胶芯为黑色



TITLE	PART. NO	DEFERENCE
SD Push Push conn. (A tpyle)	SD01-AP1**-**	POST Ø1.45
SD Push Push conn. (B tpyle)	SD02-AP1**-**	POST Ø1.35



GENERAL TOLERANCE		DWG.NO.	SD01-AP100-00	PART.NO.	SD01-AP1**-**	DRAWN	zgm 11/05'06	UNIT	mm	SCALE	NO SCALE
x.±0.50	x. °±5 °	REV.	A	TITLE	SD Push Push conn.(A TYPE)	CHECKED	曾广明 11/06`06	 DongGuang Mstconn Technology co.,LTD			
.x±0.25	.x °±2 °	SIZE	A4	SHEET	1 OF 1	APPROVED	曾广明 11/06`06				
.xx±0.15	.xx ±1 °	A4									



SPECIFICATION

- 1.Material:
 Insulator: LCP, rated UL94V-0,color:black.
 Contacts: Phosphor Bronze,
 Tin 160u" at Solder Tail,
 Selected Gold on Contact Area Plating.
 Ground:Phosphor Bronze,Tin 160u".
 Shell: Stainless.
- 2.Electrical Characteristics:
 Operating voltage : 250V(AC/DC).
 Current rating : 0.5 A.
 Operating Temperature: -20°C~+65°C.
 Insulation resistance: 1000M ohms min. at 250VDC
 Dielectric withstanding voltage:500 VAC/1minute.
 Contact resistance: 100m ohms max.
 Mating cycle: 10000 cycles, spring is not breaking.

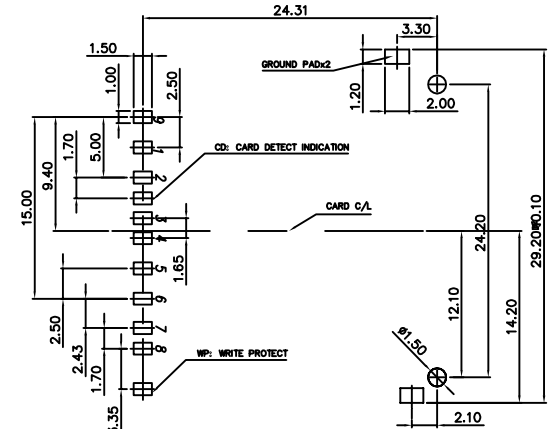
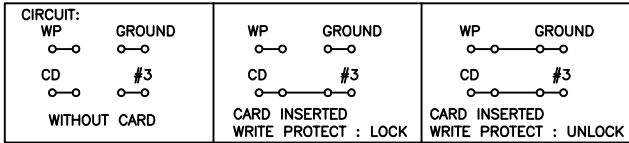
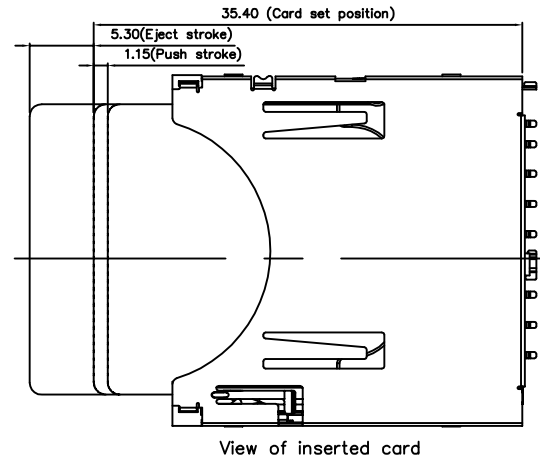
Pin No.	SD	MMC
P1	MMC-DAT3 SD-CD/DAT3	1P 1P
P2	MMC-CMD SD-CMD	2P 2P
P3	MMC-VSS1 SD-VSS1	3P 3P
P4	MMC-VDD SD-VDD	4P 4P
P5	MMC-CLK SD-CLK	5P 5P
P6	MMC-VSS2 SD-VSS2	6P 6P
P7	MMC-DAT0 SD-DAT0	7P 7P
P8	SD-DAT1	8P
P9	SD-DAT2	9P

PART. NO. :

SD02-AP1**-**

- 44: 功能区镀金5U", 锡脚镀亮纯锡至少160U"
- 45: 功能区镀金10U", 锡脚镀亮纯锡至少160U"
- 01: 胶芯为黑色

TITLE	PART. NO	DEFERENCE
SD Push Push conn. (A tylie)	SD01-AP1**-**	POST \varnothing 1.45
SD Push Push conn. (B tylie)	SD02-AP1**-**	POST \varnothing 1.35



GENERAL TOLERANCE	TOLERANCE	DWG.NO.	SD02-AP100-00	PART.NO.	SD02-AP1**-**	DRAWN	zgm 11/05'06	UNIT	mm	SCALE	NO SCALE
x. \pm 0.50	x. \circ \pm 5 $^{\circ}$	REV.	A	TITLE	SD Push Push conn.(B TYPE)	CHECKED	曾广明 11/06`06	 DongGuang Mstconn Technology co.,LTD			
.x \pm 0.25	.x \circ \pm 2 $^{\circ}$	SIZE	A4	SHEET	1 OF 1	APPROVED	曾广明 11/06`06				
.xx \pm 0.15	.xx \pm 1 $^{\circ}$	A4									

产品尺寸检验报告(FAI)

日期 Date:2006.10.09

品名 Description		SD Push Push conn.(A type)		料号 Part No.		SD01-AP1**_**		图号 Part No.		SD01-AP100-00	
样品来源 Samples Source		<input type="checkbox"/> 外購outsourcing <input type="checkbox"/> 自製Factory		样品数 Sample Size		4PCS		版次 REV		A	
项次 Item	图位 Loc.	规格 Specification	檢驗結果 Test Result (单位Unit: mm)				判定		备注 Remark		
			1	2	3	4	OK	NG			
1.)		1.70±0.15	1.715	1.721	1.719	1.714	OK				
2.)		2.42±0.15	2.406	2.413	2.409	2.407	OK				
3.)		5.00±0.15	5.011	5.019	5.013	5.016	OK				
4.)		15.00±0.15	14.929	14.937	14.931	14.935	OK				
5.)		8.60±0.15	8.615	8.613	8.621	8.629	OK				
6.)		5.00±0.15	5.092	5.084	5.086	8.094	OK				
7.)		1.16±0.15	1.221	1.193	1.189	1.211	OK				
8.)		29.1±0.25	29.212	29.241	29.197	29.256	OK				
9.)		2.70±0.15	2.746	2.731	2.799	2.717	OK				
10.)		0.74±0.15	0.754	0.763	0.741	0.736	OK				
11.)		24.15±0.15	24.221	24.235	24.217	24.256	OK				
12.)		1.45±0.15	1.438	1.456	1.437	1.431	OK				
13.)		28.9±0.25	28.94	28.97	28.96	28.92	OK				
14.)		28.90±0.15	28.94	28.97	28.91	28.98	OK				
15.)		23.50±0.15	23.512	23.546	23.559	23.528	OK				
16.)		2.10±0.15	2.116	2.172	2.161	2.136	OK				
17.)		12.85±0.15	12.879	12.880	12.817	12.864	OK				
18.)		11.30±0.15	11.347	11.391	11.354	11.323	OK				
19.)		3.30±0.15	3.329	3.337	3.319	3.362	OK				
20.)											
21.)											
22.)											
23.)											
24.)											
25.)											
26.)											
27.)											
28.)											
備註:											
核定 Approved By		曾广明 10/10`06		審查 Checked By		曾广明 10/10`06		檢驗員 Inspected By		纪芳	

产品尺寸检验报告(FAI)

日期 Date:2006.11.15

品名 Description		SD Push Push conn.(B type)		料号 Part No.		SD02-AP1**-**		图号 Part No.		SD02-AP100-00	
样品来源 Samples Source		□外購outsourcing □自製Factory		样品数 Sample Size		4PCS		版次 REV		A	
项次 Item	图位 Loc.	规格 Specification	檢驗結果 Test Result (单位Unit: mm)				判定		备注 Remark		
			1	2	3	4	OK	NG			
1.)		1.70±0.15	1.716	1.721	1.719	1.717	OK				
2.)		2.42±0.15	2.416	2.423	2.409	2.411	OK				
3.)		5.00±0.15	5.040	5.019	5.042	5.024	OK				
4.)		0.04±0.15	0.0431	0.0417	0.0422	0.0429	OK				
5.)		15.00±0.15	15.033	15.031	15.043	15.042	OK				
6.)		8.65±0.15	8.674	8.643	8.695	8.627	OK				
7.)		5.00±0.15	5.014	5.019	5.033	5.041	OK				
8.)		1.16±0.15	1.182	1.147	1.159	1.148	OK				
9.)		29.1±0.25	29.19	29.13	19.2	29.17	OK				
10.)		2.70±0.15	2.734	2.751	2.763	2.742	OK				
11.)		28.90±0.15	28.95	28.92	28.94	28.97	OK				
12.)		0.74±0.15	0.731	0.756	0.749	0.743	OK				
13.)		24.15±0.15	24.162	24.171	24.158	24.173	OK				
14.)		1.35±0.15	1.336	1.329	1.347	1.359	OK				
15.)		28.9±0.15	28.93	29.85	29.81	28.95	OK				
16.)		3.30±0.15	3.342	3.327	3.359	3.364	OK				
17.)		11.30±0.15	11.319	11.357	11.387	11.326	OK				
18.)		12.85±0.15	12.873	12.846	12.855	12.842	OK				
19.)		2.10±0.15	2.136	2.152	2.151	2.119	OK				
20.)		23.50±0.15	23.514	23.498	23.521	23.532	OK				
21.)											
22.)											
23.)											
24.)											
25.)											
26.)											
27.)											
28.)											
備註:											
核定 Approved By		曾广明 11/16`06		審查 Checked By		曾广明 11/16`06		???		纪芳	

鉅明科技有限公司

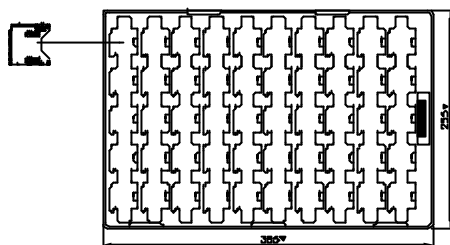
包裝作業規範

品名	SD PUSH PUSH CONN(A/B TYPE)
料號	SD01-AP1**-** SD02-AP1**-**

真空盤料號	W02-0001
紙箱料號	W01-0001

包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

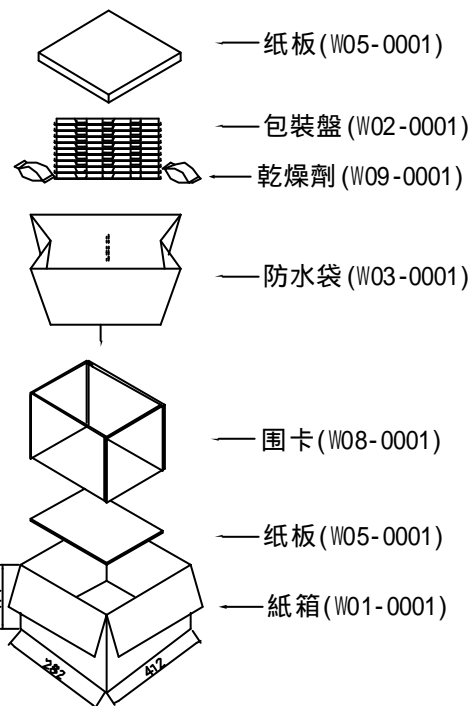
- 一.
- 1) 將成品一一放入包裝盤內,依同一方向放入 .
 - 2) 包裝時,如圖所示 .
 - 3) 一個包裝盤放置 50 個成品 .



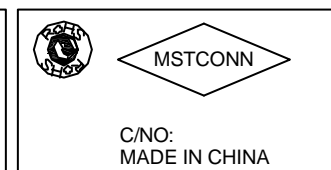
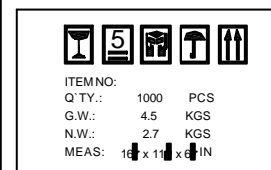
- 二.
- 1) 將放滿成品的包裝盤依同一方向一層層疊好.
 - 2) 如圖所示 .



- 三.
- 1) 每箱需放置 21 個包裝盤 .
 - 2) 最上面一個包裝盤作為上蓋,固不放置成品 .
 - 3) 每箱放置 1000 PCS 的成品 .
 - 4) 將成品放置塑膠袋內,上下面各放一包乾燥劑,包裝完後再裝箱 .



- 四.
- 1) 用TAPE將紙箱封實 .



備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿 .

GENERAL TOLERANCE		FILE.NO.	3C-ENW003A	PART.NO.	SD01/02-AP1**-**	DRAWN	JIFang 2006.11.08	MATERIAL		SCALE	
x. ± 0.35	x. ± 5°	REV.	A	TITLE	SD Push Push conn(A/B TYPE)	CHECKED	曾广明 11/09'06	DATE	2006.11.08	UNIT	mm
.x ± 0.25	.x ± 2°	SIZE		SHEET	1 OF 1	APPROVED	曾广明 11/09'06	MSTCONN 东莞鉅明科技有限公司 Dongguan Mstconn Technology CO., LTD			
.xx ± 0.15	.xx ± 1°	A4									